

ABSTRACT OF THE INVENTION

A method for preparing an encapsulated electronic component using a reworkable encapsulant composition comprising a major amount of mono-functional maleimide
5 compounds, or mono-functional vinyl compounds other than maleimide compounds, or a combination of mono-functional maleimide and vinyl compounds, a curing initiator and optionally, one or more fillers or adhesion promoters comprising curing the composition in situ.

This Sheet Has Been Replaced



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